Amendments to the Specification:

Please replace the paragraph beginning on page 3, line 15 with the following amended paragraph:

-- Fig. 2 is an [[and]] exemplary plan view of a lead frame that may be used within the semiconductor power module shown in Fig. 1; [[and]] --

Please replace the paragraph beginning on page 3, line 17 with the following amended paragraph:

-- Fig. 3 is an exemplary cross-sectional diagrammatic view of a semiconductor power module according to another embodiment of the invention; [[.]] --

Please add the following new paragraphs beginning on page 3, line 20:

-- Fig. 4 is an exemplary cross-sectional diagrammatic view of a semiconductor power module according to a further embodiment of the invention; and

Fig. 5 is an exemplary cross-sectional diagrammatic view of a semiconductor power module according to yet another embodiment of the invention. --

Please replace the paragraph beginning on page , with the following amended paragraph:

-- After application of the sealer 60, the insulator 70, which may be sheet shaped, is adhered adjacent to the bottom surface of the lead frame 40 near the first portion 41. In operation, the insulator 70 functions as a heat sink and effectively dissipates the loss heat generated by the power semiconductor element 11. Additionally, the insulator 70 functions to evenly distribute stresses from external impacts to prevent the occurrence of cracks and other types of damage to the power semiconductor module 100. In some embodiments, the insulator 70 may be adhered to the lead frame 40 as shown in Fig. 4 using an adhesive containing a filler such as Al_2O_3, AlN, or BeO, which provide good electrical insulation properties and good thermal conductivity. Further, the insulator 70 may be bent to prevent deflection transformation thereof caused by adherence of other materials thereto. In other embodiments, the sealer 60 and the insulator 70 may have rings or grooves that enable the insulator 70 to be detachably mounted (e.g., pressed on, threaded on, etc.) to the semiconductor power module 100 as shown in Fig. 5. --